

**AMENDMENT TO THE CLAIMS**

1. (Currently amended) A plasma display panel (PDP) adopting an AC surface discharge method comprising:

a scan electrode and a sustain electrode both formed on a plate and to which a voltage is applied in order to generate discharge;

a dielectric layer covering ~~[[a]]~~ the scan electrode and ~~[[a]]~~ the sustain electrode ~~both formed on a plate;~~ and

a protective layer formed on the dielectric layer,

wherein the protective layer is made of magnesium oxide (MgO) includes including silicon (Si) and nitrogen (N).

2. (Currently amended) The PDP adopting an AC surface discharge method as defined in claim 1, wherein the protective layer is made of magnesium oxide (MgO) including Si of which atoms count in a range from  $5 \times 10^{18}$  pieces/cm<sup>3</sup> to  $2 \times 10^{21}$  pieces/cm<sup>3</sup>, and N of which atoms count in a range from  $1 \times 10^{18}$  pieces/cm<sup>3</sup> to  $8 \times 10^{21}$  pieces/cm<sup>3</sup>.

3. (Currently amended) A method of manufacturing a plasma display panel (PDP) adopting an AC surface discharge method, the method comprising the steps of:

forming a scan electrode and a sustain electrode on a plate;

applying to the scan electrode and the sustain electrode a voltage in order to generate discharge; and

forming a dielectric layer to cover ~~[[a]]~~ the scan electrode and ~~[[a]]~~ the sustain electrode ~~both formed on a plate;~~ and

forming a protective layer on the dielectric layer,

wherein the step of forming the protective layer is a process for forming a film that uses material of the protective layer, which material is made of magnesium oxide (MgO) ~~includes~~ including silicon (Si) and nitrogen (N).

4. (Currently amended) The method of manufacturing a PDP adopting an AC surface discharge method as defined in claim 3, wherein the material of the protective layer is made of magnesium oxide (MgO) including Si and N,

wherein a concentration of the Si falls within a range from 7 weight ppm to 8000 weight ppm, and a concentration of the N falls within a range from 4 weight ppm to 6000 weight ppm.

5. (Currently amended) The method of manufacturing a PDP adopting an AC surface discharge method as defined in claim 3, wherein the material of the protective layer is made of magnesium oxide (MgO) including silicon nitride ( $\text{Si}_3\text{N}_4$ ) of which concentration falls within a range from 10 weight ppm to 15000 weight ppm.

6. (Currently amended) Material of a protective layer of a plasma display panel adopting an AC surface discharge method, the plasma display panel comprising a scan electrode and a sustain electrode both formed on a plate and to which a voltage is applied in order to generate a discharge, wherein:

the protective layer is formed on ~~[[a]]~~ the dielectric layer which covers ~~[[a]]~~ the scan electrode and ~~[[a]]~~ the sustain electrode ~~both formed on a plate, wherein~~

the material is made of magnesium oxide (MgO) includes including silicon (Si) and nitrogen (N).

7. (Currently amended) The material of the protective layer of a plasma display panel adopting an AC surface discharge method as defined in claim 6, which material is made of magnesium oxide (MgO) including Si and N, wherein a concentration of the Si falls within a range from 7 weight ppm to 8000 weight ppm, and a concentration of the N falls within a range from 4 weight ppm to 6000 weight ppm.

8. (Currently amended) The material of the protective layer of a plasma display panel adopting an AC surface discharge method as defined in claim 6, which material is made of magnesium oxide (MgO) including silicon nitride ( $\text{Si}_3\text{N}_4$ ) of which concentration falls within a range from 10 weight ppm to 15000 weight ppm.